

L13	141	thin\$1film with (structure substrate board) and (frame plate carrier holder support\$2) near4 (temporary remov\$4 detach\$4) and (insulat\$3 dielectric ceramic organic) near4 (frame plate dam ring)	USPAT; EPO; JPO	OR	ON	2004/11/23 12:17
L14	75	thin\$1film same (frame plate carrier holder support\$2) near4 (temporary remov\$4 detach\$4) and (insulat\$3 dielectric ceramic organic) near4 (board substrate frame plate)	USPAT; EPO; JPO	OR	ON	2004/11/23 12:23
L15	24	("4812191"   "4914814"   "5056215"   "5060844"   "5116459"   "5154341"   "5170931"   "5258236"   "5306872"   "5338900"   "5342713"   "5347162"   "5368963"   "5409157"   "5427876"   "5464712"   "5521032"   "5534094"   "5534466"   "5565286"   "5633535"   "5700715"   "5861666"   "5994168").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/11/23 12:20
L16	24	thin\$1film with module and (frame plate carrier holder support\$2) near4 (temporary remov\$4 detach\$4) and (insulat\$3 dielectric ceramic organic) near4 (board substrate frame plate)	USPAT; EPO; JPO	OR	ON	2004/11/23 12:31
L17	1	"6769174".pn.	USPAT; EPO; JPO	OR	ON	2004/11/23 12:31
L18	7	("20020027010"   "20020100165"   "5218759"   "5480503"   "5620928"   "6130473"   "6247229").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/11/23 12:31
S1	13	Giri.in. and chip with module	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2004/11/16 12:31
S2	12	("5633532"   "5710071"   "5834334"   "5985693"   "6010951"   "6281042"   "6281452"   "6291268"   "6304232"   "6347037"   "6376917"   "6424034").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/11/16 12:33
S3	95	multi\$1chip near3 module same carrier same (ic chip semiconductor) and opposite near3 surface	USPAT; USOCR; EPO; JPO	OR	ON	2004/11/16 12:42
S4	36	S3 and frame	USPAT; USOCR; EPO; JPO	OR	ON	2004/11/16 12:38
S5	3	multi\$1chip near3 module same thin\$1film same carrier same (ic chip semiconductor) and (both opposite) near3 surface	USPAT; USOCR; EPO; JPO	OR	ON	2004/11/16 12:44

S6	11	multi\$1chip near3 module same carrier same (ic chip semiconductor) and (both opposite) near3 surface and (remov\$3 strip\$4) near3 carrier	USPAT; USOCR; EPO; JPO	OR	ON	2004/11/16 12:45
S7	12	("5633532" "5710071" "5834334" "5985693" "6010951" "6281042" "6281452" "6291268" "6304232" "6347037" "6376917" "6424034").PN.	USPAT; EPO; JPO	OR	ON	2004/11/22 14:39
S8	78	(thin\$1film multi\$1layer) near3 (structure board substrate) same (carrier plate holder) same (frame damp) same (ic chip semiconductor)	USPAT; EPO; JPO	OR	ON	2004/11/22 15:39
S9	51	(thin\$1film multi\$1layer) near3 (structure board substrate) with (carrier plate holder) and (frame damp spacer) same (ic chip semiconductor) and (remov\$4 detach\$3) with (carrier plate holder)	USPAT; EPO; JPO	OR	ON	2004/11/22 16:18
S10	165	(thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and (frame damp spacer) same (ic chip semiconductor)	USPAT; EPO; JPO	OR	ON	2004/11/22 16:20
S11	96	(thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and (frame damp spacer) same (ic chip semiconductor) and (second oppos\$4) near3 surface	USPAT; EPO; JPO	OR	ON	2004/11/22 17:12
S12	8	("3781596"   "4549200"   "4931853"   "5048179"   "5123850"   "5138433"   "5196992"   "5239198").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/11/22 16:58
S13	156	("5239198").URPN.	USPAT	OR	ON	2004/11/22 17:00
S14	9	29/830-832.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) same (ic chip semiconductor)	USPAT; EPO; JPO	OR	ON	2004/11/22 17:15
S15	28	"174"/\$.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) same (ic chip semiconductor)	USPAT; EPO; JPO	OR	ON	2004/11/22 17:18

S16	53	"361"/\$.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) same (ic chip semiconductor)	USPAT; EPO; JPO	OR	ON	2004/11/22 17:20
S17	171	"257"/\$.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) same (ic chip semiconductor)	USPAT; EPO; JPO	OR	ON	2004/11/22 17:20
S18	171	"257"/\$.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) same (ic chip semiconductor)	USPAT; EPO; JPO	OR	ON	2004/11/22 18:47
S19	1	thin\$1film near3 (structure board substrate multi\$1layer) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and mounting with (ic chip semiconductor) same (both oppos\$3) near2 (surface face)	USPAT; EPO; JPO	OR	ON	2004/11/22 18:49
S20	14	thin\$1film near3 (structure board substrate multi\$1layer) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and mounting with (ic chip semiconductor)	USPAT; EPO; JPO	OR	ON	2004/11/22 18:50
S21	16	thin\$1film near3 (structure board substrate multi\$1layer) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and (insulat\$3 dielectric) near3 (stifferner frame damp spacer) and (ic chip semiconductor)	USPAT; EPO; JPO	OR	ON	2004/11/22 18:51